



Material Content Data Sheet



Sales Product Name		IPP50N12S3L-15		Issued		25. January 2018		
MA#		MA001400660						
Package		PG-TO220-3-1		Weight*		2041.54 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.497	0.22	0.22	2203	2203
leadframe	non noble metal	iron	7439-89-6	0.816	0.04		400	
	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	copper	7440-50-8	815.335	39.95	40.00	399371	399892
wire	non noble metal	aluminium	7429-90-5	53.486	2.62	2.62	26199	26199
encapsulation	organic material	carbon black	1333-86-4	8.268	0.40		4050	
	plastics	epoxy resin	-	90.952	4.46		44551	
	inorganic material	silicondioxide	60676-86-0	452.006	22.14	27.00	221404	270005
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10513	10513
plating	non noble metal	nickel	7440-02-0	0.244	0.01		120	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	120
solder	noble metal	silver	7440-22-4	0.100	0.00		49	
	non noble metal	tin	7440-31-5	0.080	0.00		39	
	non noble metal	lead	7439-92-1	3.816	0.19	0.19	1869	1957
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		289	
	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	copper	7440-50-8	589.466	28.87	28.91	288735	289111
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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